



National Aeronautics and
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Glenn Research Center

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Ka-Band Wide-Bandgap Solid-State Power Amplifier Technology

Jet Propulsion Laboratory

Mid-Year Review

Pasadena, California

January 27, 2004



National Aeronautics and
Space Administration
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Agenda

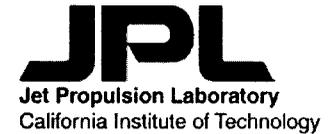
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- Welcome
 - Task Overview
 - JPL Design Task
 - Requirements
 - Architectures
 - Detailed Analyses
 - Break
 - Discussion
 - GRC Design Task
 - Overview
 - Notional Architectures
 - Thermal/MMIC Analysis
 - Feedback & Wrap-Up



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Welcome



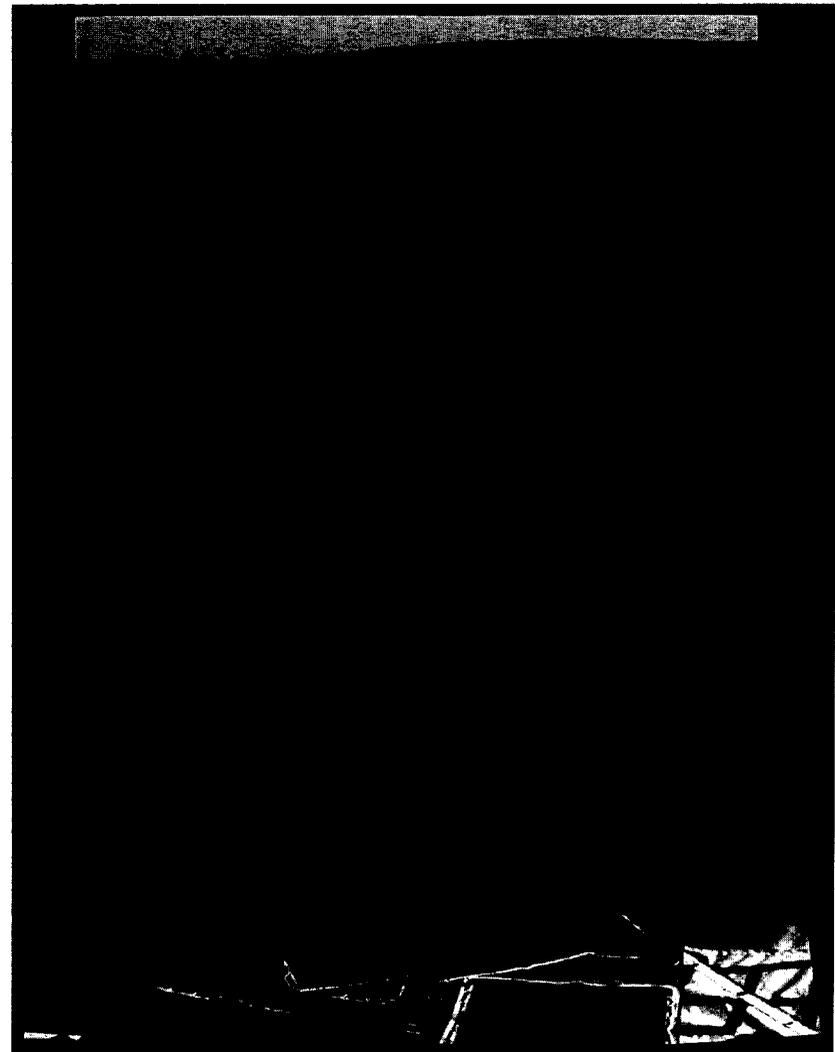
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- JPL welcomes partner contractors, sponsors, interested parties and guests.
 - Purpose & Goals
 - Communicate task status
 - Describe key accomplishments
 - Define future plans
 - JPL is a partner contractor for WBG SSPA Study
 - Partner Contractors
 - HRL
 - NGST
 - NASA Glenn is the JPL Managing Organization
 - Also plays a technical role



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A Key Accomplishment

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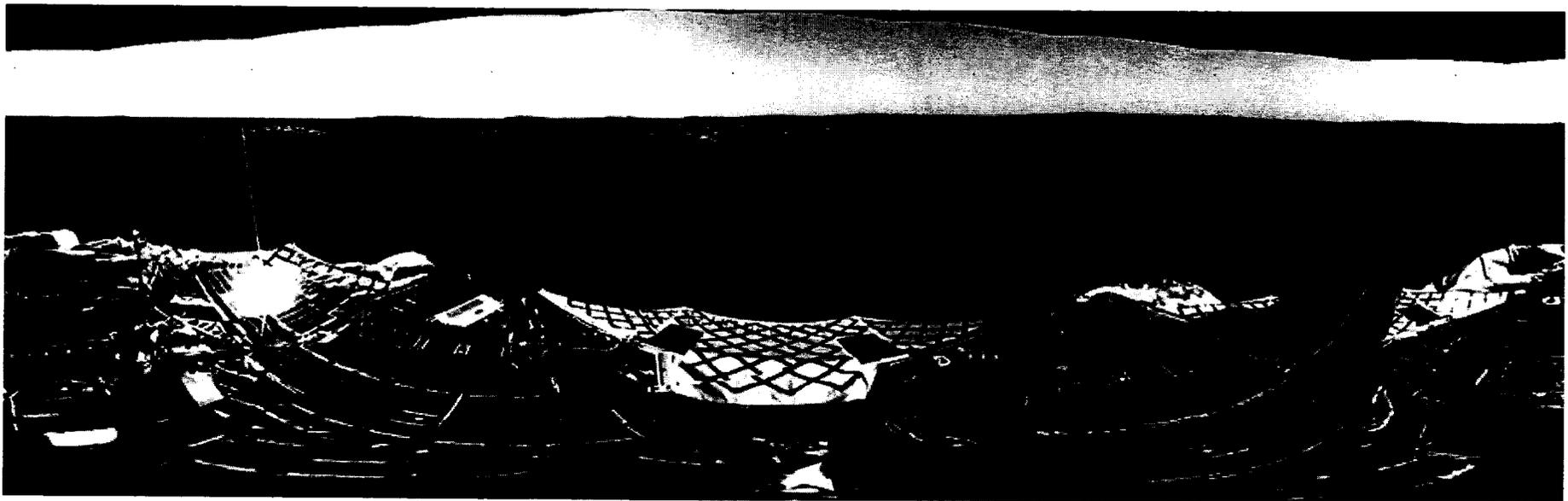
WBG SSPA Study Mid-Year Review



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First Panoramic Look

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Meridiani Planum, Mars



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TASK OVERVIEW



Program Objective

To determine the feasibility of a WBG semiconductor based 120–150 W Ka-band SSPA as an alternative for space TWTA's with an engineering model build in 3–5 years leading to a flight model build in 7–8 years.

Target SSPA

	PARAMETER	VALUE	NOTE	<u>35 W TWTA</u>	<u>100 W TWTA</u>
1	Power Output	120 to 150 Watts		35 Watts	100 Watts
2	Power Added Efficiency	40%	@P _{1dB}	52% (46% w/EPC)	60%
3	Band of Operation	31 to 36 GHz		31.8-32.3 GHz	31.8-32.3 GHz
4	Bandwidth	10%			
5	Gain	50 dB		51 dB	50 dB
6	Noise Figure	<20dB			
7	AM/PM Conversion	<2°/dB		<4°/dB	<4°/dB
8	Phase Ripple	<3° peak to peak			
9	Input Bus voltage	50 Volts±5 Volts	DC	28 V±4 V	
10	Mass	< 4 kg	incl. EPC	2.5 kg	2.5 kg
11	Environment	GEO or Deep Space			

Additional architecture-dependent requirements include redundancy, graceful degradation, and adequate thermal management.

Noise figure, AM/PM conversion, bus voltage and radiation tolerance are primarily MMIC/semiconductor technology driven.



SSPA Study Task Status

SOW TASK 1: Architecture Identification

- Reviewed over 100 published articles relevant to millimeter-wave power combining and have begun focusing on three general architectures for further detailed study
- Delivered report of findings to sponsor (11/7/03)

SOW TASK 2a: Detailed Architecture Considerations

- Defined sub-system requirements and trade space
- Currently evaluating electrical performance of architectures identified in task 1 at component and system levels (80% complete)
- Have started to evaluate mechanical and thermal performance

SOW TASK 2b: MMIC Considerations

- Established subcontract with Rock Systems LLC to evaluate WBG reliability status and identify critical path/develop roadmap for insertion into high-reliability applications



GaN Reliability Subcontract

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- Contract established with Rock Systems LLC, December, 2003
 - S. Kayali (JPL), G. Ponchak (GRC), R. Shaw (Rock Systems), “GaAs MMIC Reliability Assurance Guideline for Space Applications”
 - Reliability Lead – Roland Shaw, Rock Systems LLC
 - 6 month study of WBG device reliability status and roadmap
 - Phase I results due 2/3/04
 - Current reliability status of GaN broad state-of-the art devices and comparison with GaAs technology
 - Critical path for GaN insertion in space and high-reliability applications
 - Phase II results due 7/10/04
 - Recommendation for core reliability guideline for WBG RF semiconductors
 - Possible failure mechanisms
 - Accelerated life test methodology requirements
 - Critical development roadmap required for 3-5 year technology insertion
 - Phase I results will be included in NASA interim report #2



Progress Summary

-
- We have examined promising architectures and believe we can meet requirements outlined for the program
 - Low combiner losses (approximately < 1.0 dB total)
 - Projected GaN MMIC performance (not outside the realm of possibility)
 - Advances still required
 - Challenges still ahead
 - PAE is what may differentiate WBG technologies at Ka-band to be competitive with the tube
 - A lower power MMIC (3W) but high PAE (greater than 40%) may afford a reasonable compromise in terms of thermal footprint and graceful degradation
 - May be the most viable approach consistent with the customer timeline
 - Important next steps in the current phase are key component proof of concept hardware demonstrators and modeling for high efficiency
 - Combining circuits
 - Thermal studies



Phase I Schedule

Tasks	Months after start of contract											
	1	2	3	4	5	6	7	8	9	10	11	12
	AUG	SEP	OCT	NOV	DEC	JAN	FEB	MAR	APR	MAY	JUN	JUL
1. Architecture Identification	█	█	█									
2. Detailed Analysis				█	█	█	█	█	█	█		
3. Hardware Validation							█	█	█	█	█	
4. Technology Roadmap											█	█



- **Task Start: August 4, 2003**
- **Task 1 – Architecture identification, completed**
 - Interim Report #1 delivered November 7, 2003
- **Task 2a – Detailed analyses of selected architectures currently underway**
- **Task 2b – WBG technology review**
 - Reliability study subcontract established
- **Interim report #2 on detailed analysis due March 2004**



SSPA Roadmap

JPL Task Plans	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Phase I Activity -SSPA Arch		⇐								
Task 1 - Arch Identification										
Task 2 - Detailed Arch Considerations										
Task 3 - Hardware Eval										
Task 4 - Roadmap Report										
Phase II Activity - 120 W Breadboard		⇐								
Detailed SSPA Design										
Fab/Integration										
Perf Test										
Long-term Reliability Evaluations										
Phase III Activity - EM/Brassboard			⇐							
SSPA Des Optimizations										
HPE/EPC Design										
Mech/Thermal/Packaging										
Radiation & Space Qual/ESS										
Phase IV Activity - Protoflight Model Dev						⇐				
	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012

WBG SSPA Roadmap



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